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Details

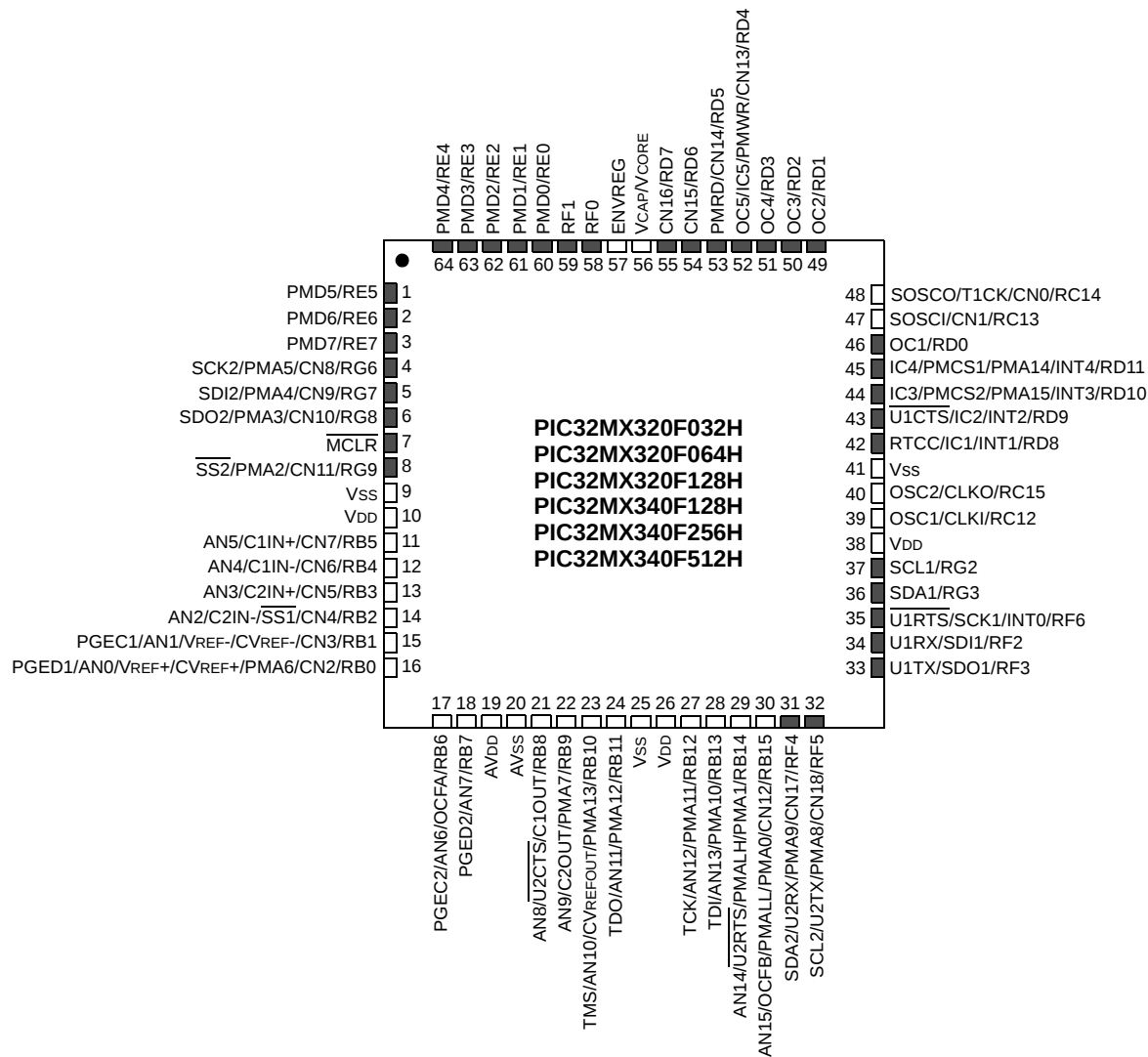
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx340f512h-80v-pt

PIC32MX3XX/4XX

Pin Diagrams

64-Pin QFN (General Purpose)

■ = Pins are up to 5V tolerant



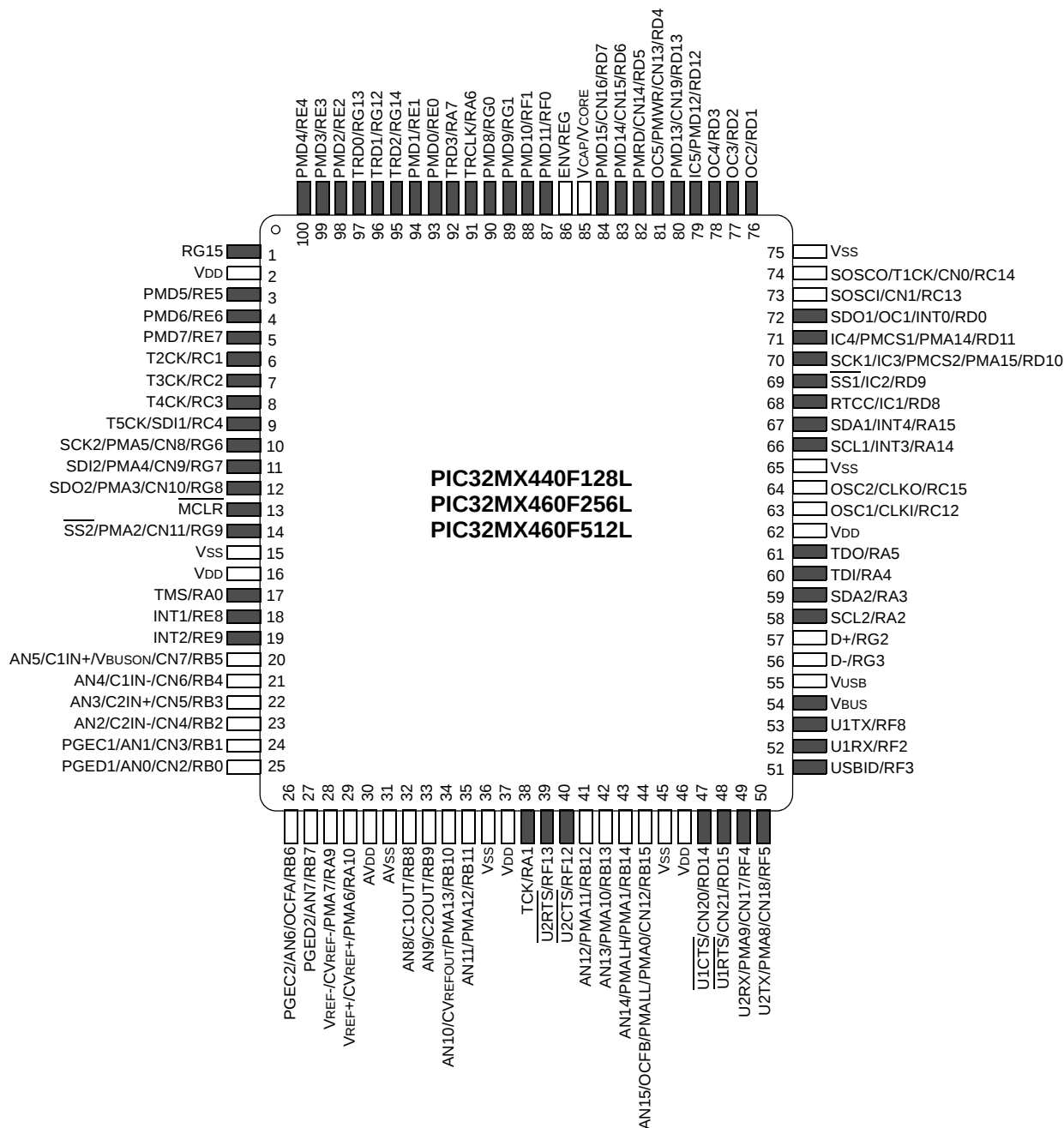
Note: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

PIC32MX3XX/4XX

Pin Diagrams (Continued)

100-Pin TQFP (USB)

■ = Pins are up to 5V tolerant



PIC32MX3XX/4XX

Table of Contents

1.0	Device Overview	21
2.0	Guidelines for Getting Started with 32-bit Microcontrollers	31
3.0	CPU	37
4.0	Memory Organization	43
5.0	Flash Program Memory	85
6.0	Resets	87
7.0	Interrupt Controller	89
8.0	Oscillator Configuration	93
9.0	Prefetch Cache	95
10.0	Direct Memory Access (DMA) Controller	97
11.0	USB On-The-Go (OTG)	99
12.0	I/O Ports	101
13.0	Timer1	103
14.0	Timer2/3 and Timer4/5	105
15.0	Input Capture	107
16.0	Output Compare	109
17.0	Serial Peripheral Interface (SPI)	111
18.0	Inter-Integrated Circuit™ (I ² C™)	113
19.0	Universal Asynchronous Receiver Transmitter (UART)	115
20.0	Parallel Master Port (PMP)	119
21.0	Real-Time Clock and Calendar (RTCC)	121
22.0	10-bit Analog-to-Digital Converter (ADC)	123
23.0	Comparator	125
24.0	Comparator Voltage Reference (CVREF)	127
25.0	Power-Saving Features	129
26.0	Special Features	131
27.0	Instruction Set	141
28.0	Development Support	147
29.0	Electrical Characteristics	151
30.0	Packaging Information	191
	Index	209

2.9 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as “digital” pins by setting all bits in the ADPCFG register.

The bits in this register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 2, ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain Analog-to-Digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the ADPCFG register during initialization of the ADC module.

When MPLAB ICD 2, ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the ADPCFG register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all Analog-to-Digital pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.10 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternately, inputs can be reserved by connecting the pin to Vss through a 1k to 10k resistor and configuring the pin as an input.

2.11 Referenced Sources

This device data sheet is based on the following individual chapters of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the PIC32MX460F512L product page on the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS61127)
- **Section 2. "CPU"** (DS61113)
- **Section 3. "Memory Organization"** (DS61115)
- **Section 4. "Prefetch Cache"** (DS61119)
- **Section 5. "Flash Program Memory"** (DS61121)
- **Section 6. "Oscillator Configuration"** (DS61112)
- **Section 7. "Resets"** (DS61118)
- **Section 8. "Interrupt Controller"** (DS61108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS61114)
- **Section 10. "Power-Saving Features"** (DS61130)
- **Section 12. "I/O Ports"** (DS61120)
- **Section 13. "Parallel Master Port (PMP)"** (DS61128)
- **Section 14. "Timers"** (DS61105)
- **Section 15. "Input Capture"** (DS61122)
- **Section 16. "Output Compare"** (DS61111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS61104)
- **Section 19. "Comparator"** (DS61110)
- **Section 20. "Comparator Voltage Reference (CVREF)"** (DS61109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS61107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS61106)
- **Section 24. "Inter-Integrated Circuit™ (I²C™)"** (DS61116)
- **Section 27. "USB On-The-Go (OTG)"** (DS61126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS61117)
- **Section 32. "Configuration"** (DS61124)
- **Section 33. "Programming and Diagnostics"** (DS61129)

PIC32MX3XX/4XX

TABLE 3-2: COPROCESSOR 0 REGISTERS (CONTINUED)

Register Number	Register Name	Function
17-22	Reserved	Reserved
23	Debug ⁽²⁾	Debug control and exception status
24	DEPC ⁽²⁾	Program counter at last debug exception
25-29	Reserved	Reserved
30	ErrorEPC ⁽¹⁾	Program counter at last error
31	DESAVE ⁽²⁾	Debug handler scratchpad register

Note 1: Registers used in exception processing.

2: Registers used during debug.

Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 shows the exception types in order of priority.

TABLE 3-3: PIC32MX3XX/4XX FAMILY CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{\text{MCLR}}$ or a Power-on Reset (POR)
DSS	EJTAG Debug Single Step
DINT	EJTAG Debug Interrupt. Caused by the assertion of the external <i>EJ_DINT</i> input, or by setting the <i>EjtagBrk</i> bit in the ECR register
NMI	Assertion of NMI signal
Interrupt	Assertion of unmasked hardware or software interrupt signal
DIB	EJTAG debug hardware instruction break matched
AdEL	Fetch address alignment error Fetch reference to protected address
IBE	Instruction fetch bus error
DBp	EJTAG Breakpoint (execution of SDBBP instruction)
Sys	Execution of SYSCALL instruction
Bp	Execution of BREAK instruction
RI	Execution of a Reserved Instruction
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled
CEU	Execution of a CorExtend instruction when CorExtend is not enabled
Ov	Execution of an arithmetic instruction that overflowed
Tr	Execution of a trap (when trap condition is true)
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG Data Value Break on Store (address + value)
AdEL	Load address alignment error Load reference to protected address
AdES	Store address alignment error Store to protected address
DBE	Load or store bus error
DDBL	EJTAG data hardware breakpoint matched in load data compare

TABLE 4-1: BUS MATRIX REGISTERS MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	BMX CON ⁽¹⁾	31:16	—	—	—	—	—	BMXCHEDMA	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	001F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0042
2010	BMX DKPBA ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMX DUDBA ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMX DUPBA ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMX DRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMX PUPBA ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMX PFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMX BOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	3000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET, and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-13: ADC REGISTERS MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000
9120	ADC1BUFB	31:16	ADC Result Word B (ADC1BUFB<31:0>)																0000
		15:0																	0000
9130	ADC1BUFC	31:16	ADC Result Word C (ADC1BUFC<31:0>)																0000
		15:0																	0000
9140	ADC1BUFD	31:16	ADC Result Word D (ADC1BUFD<31:0>)																0000
		15:0																	0000
9150	ADC1BUFE	31:16	ADC Result Word E (ADC1BUFE<31:0>)																0000
		15:0																	0000
9160	ADC1BUFF	31:16	ADC Result Word F (ADC1BUFF<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-14: DMA GLOBAL REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SUSPEND	—	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	—	DMACH<1:0>	—	0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-15: DMA CRC REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	PLEN<3:0>				CRCEN	CRCAPP	—	—	—	—	CRCCH<1:0>		0000
3040	DCRCDATA	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCDATA<15:0>																0000
3050	DCRCXOR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	DCRCXOR<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-25: PORTD REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L, PIC32MX360F512L, PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISD15	TRISD14	TRISD13	TRISD12	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	FFFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RD15	RD14	RD13	RD12	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATD15	LATD14	LATD13	LATD12	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCD15	ODCD14	ODCD13	ODCD12	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-26: PORTD REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX420F032H, PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
60C0	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	0FFF
60D0	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
60E0	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
60F0	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-39: PREFETCH REGISTERS MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets			
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1		16/0		
4000	CHECON ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CHECOH	0000		
		15:0	—	—	—	—	—	—	DCSZ<1:0>		—	—	PREFEN<1:0>		—	PFMWS<2:0>			0007		
4010	CHEACC ⁽¹⁾	31:16	CHEWEN	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000		
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	CHEIDX<3:0>				00xx		
4020	CHETAG ⁽¹⁾	31:16	LTAGBOOT	—	—	—	—	—	—	—	LTAG<23:16>										xxx0
		15:0	LTAG<15:4>												LVALID	LLOCK	LTYPE	—	xxx2		
4030	CHEMSK ⁽¹⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000		
		15:0	LMASK<15:5>												—	—	—	—	—	xxxx	
4040	CHEW0	31:16	CHEW0<31:0>																xxxx		
		15:0																	xxxx		
4050	CHEW1	31:16	CHEW1<31:0>																xxxx		
		15:0																	xxxx		
4060	CHEW2	31:16	CHEW2<31:0>																xxxx		
		15:0																	xxxx		
4070	CHEW3	31:16	CHEW3<31:0>																xxxx		
		15:0																	xxxx		
4080	CHELRU	31:16	—	—	—	—	—	—	—	CHELRU<24:16>										0000	
		15:0	CHELRU<15:0>																0000		
4090	CHEHIT	31:16	CHEHIT<31:0>																xxxx		
		15:0																	xxxx		
40A0	CHEMIS	31:16	CHEMIS<31:0>																xxxx		
		15:0																	xxxx		
40C0	CHEPFABT	31:16	CHEPFABT<31:0>																xxxx		
		15:0																	xxxx		

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

13.0 TIMER1

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. “Timers”** (DS61105) of the *“PIC32 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

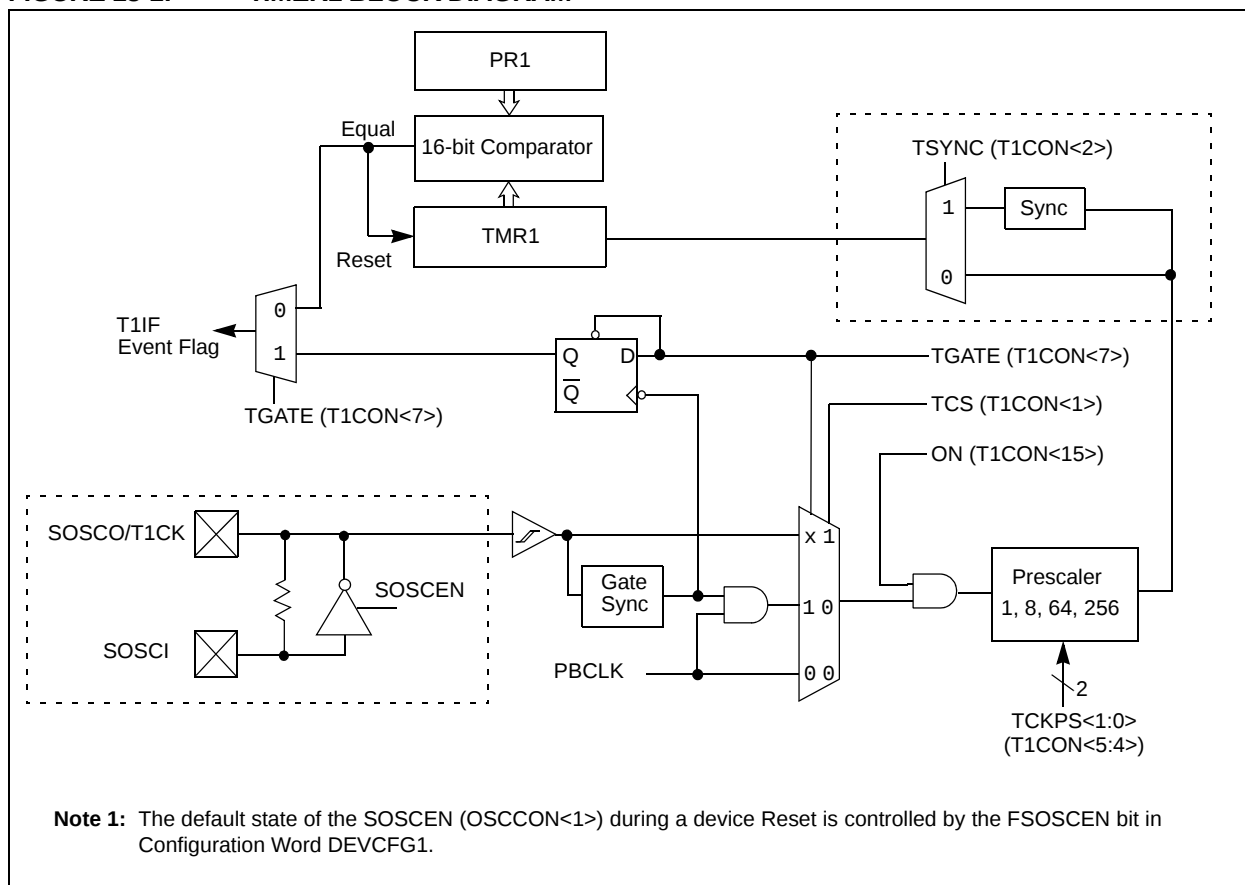
This family of PIC32MX devices features one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can also be used with the Secondary Oscillator (Sosc) for real-time clock applications. The following modes are supported:

- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

13.1 Additional Supported Features

- Selectable clock prescaler
- Timer operation during CPU Idle and Sleep mode
- Fast bit manipulation using CLR, SET and INV registers
- Asynchronous mode can be used with the Sosc to function as a Real-Time Clock (RTC)

FIGURE 13-1: TIMER1 BLOCK DIAGRAM⁽¹⁾



16.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. “Output Compare”** (DS61111) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

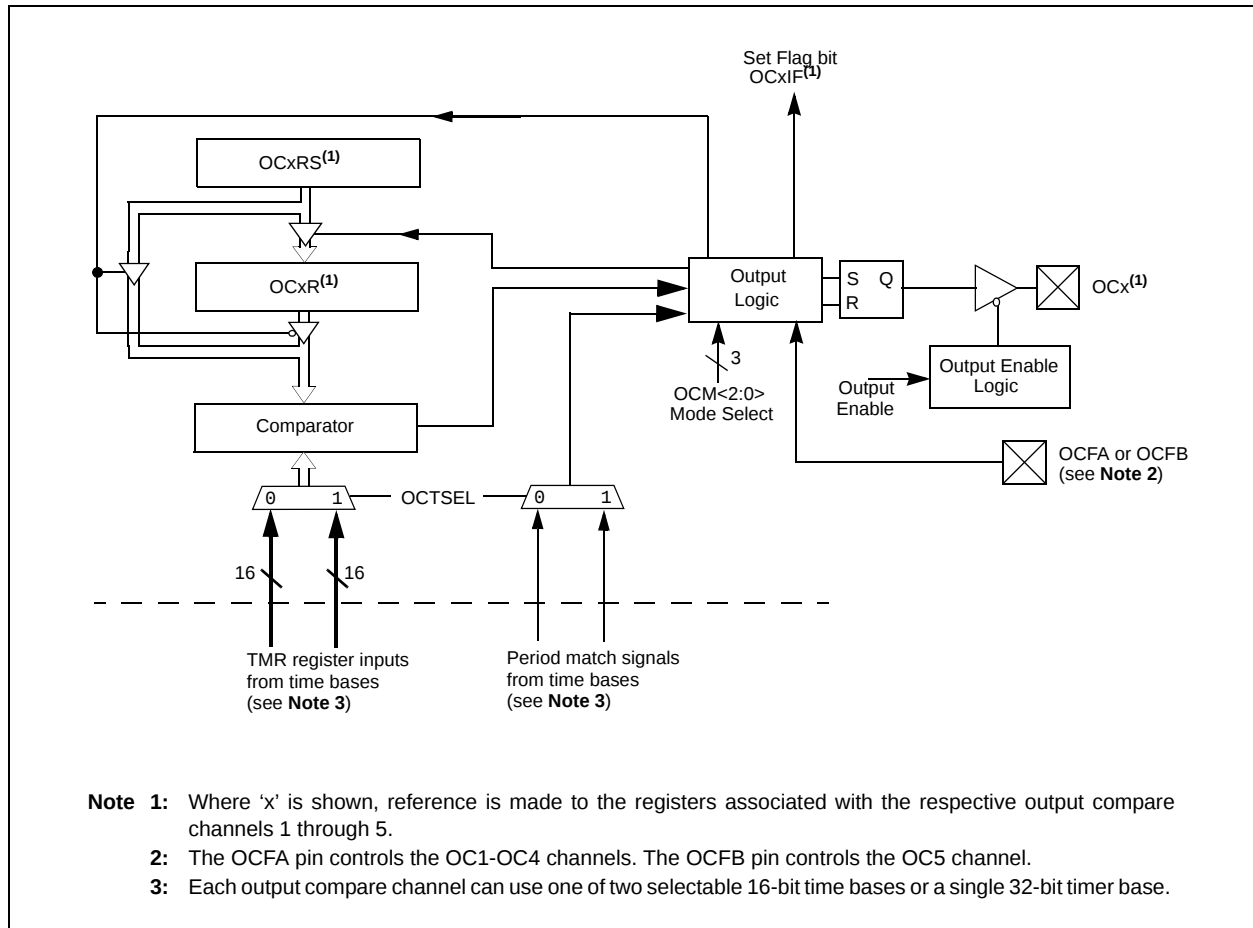
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Output Compare module (OCMP) is used to generate a single pulse or a train of pulses in response to selected time base events. For all modes of operation, the OCMP module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the OCMP module generates an event based on the selected mode of operation.

The following are some of the key features:

- Multiple output compare modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Programmable selection of 16-bit or 32-bit time bases.
- Can operate from either of two available 16-bit time bases or a single 32-bit time base

FIGURE 16-1: OUTPUT COMPARE MODULE BLOCK DIAGRAM



22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS61104) of the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The PIC32MX3XX/4XX 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1000 kilo samples per second (ksps) conversion speed
- Up to 16 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample-and-Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable Buffer Fill modes
- Eight conversion result format options
- Operation during CPU Sleep and Idle modes

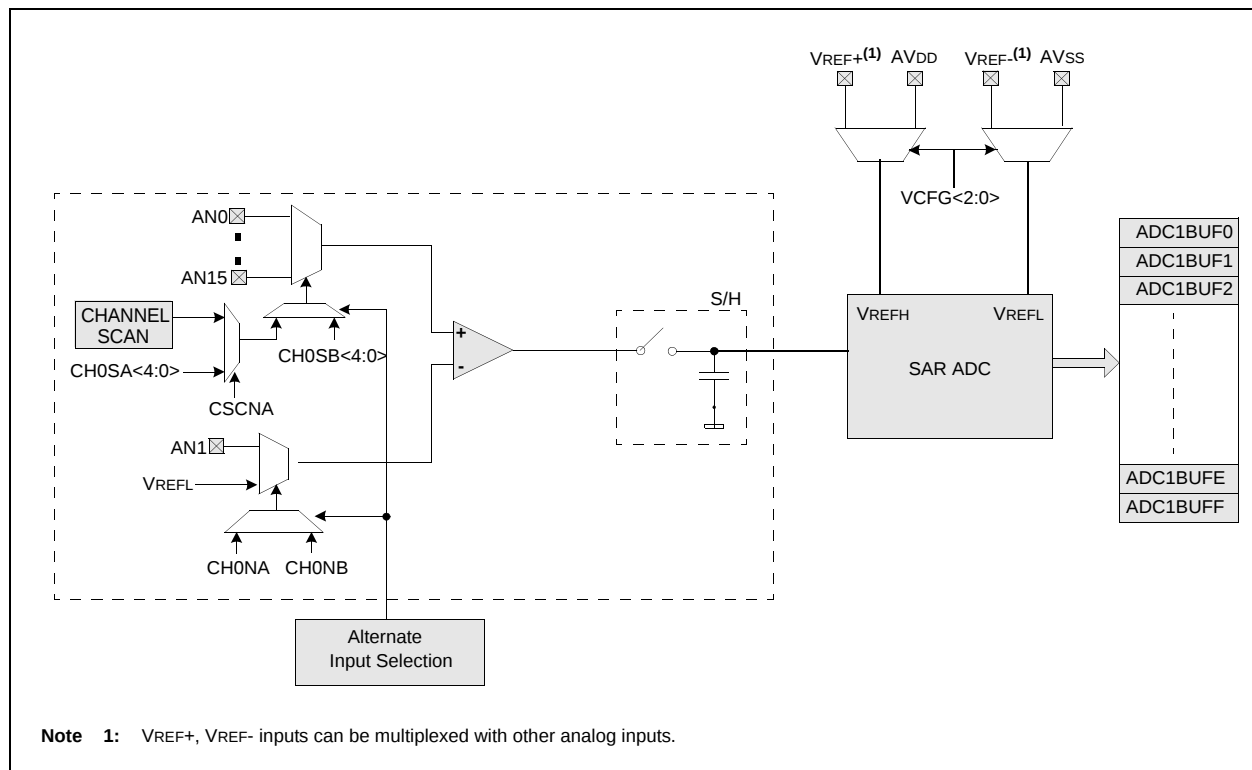
A block diagram of the 10-bit ADC is illustrated in Figure 22-1. The 10-bit ADC has 16 analog input pins, designated AN0-AN15. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

The analog inputs are connected through two multiplexers (MUXs) to one SHA. The analog input MUXs can be switched between two sets of analog inputs between conversions. Unipolar differential conversions are possible on all channels, other than the pin used as the reference, using a reference input pin (see Figure 22-1).

The Analog Input Scan mode sequentially converts user-specified channels. A control register specifies which analog input channels will be included in the scanning sequence.

The 10-bit ADC is connected to a 16-word result buffer. Each 10-bit result is converted to one of eight, 32-bit output formats when it is read from the result buffer.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



PIC32MX3XX/4XX

REGISTER 26-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 19-12 **PWP<7:0>**: Program Flash Write-Protect bits

Prevents selected program Flash memory pages from being modified during code execution. The PWP bits represent the one's complement of the number of write protected program Flash memory pages.

11111111 = Disabled
11111110 = 0xBD00_0FFF
11111101 = 0xBD00_1FFF
11111100 = 0xBD00_2FFF
11111011 = 0xBD00_3FFF
11111010 = 0xBD00_4FFF
11111001 = 0xBD00_5FFF
11111000 = 0xBD00_6FFF
11110111 = 0xBD00_7FFF
11110110 = 0xBD00_8FFF
11110101 = 0xBD00_9FFF
11110100 = 0xBD00_AFFF
11110011 = 0xBD00_BFFF
11110010 = 0xBD00_CFFF
11110001 = 0xBD00_DFFF
11110000 = 0xBD00_EFFF
11101111 = 0xBD00_FFFF
.
.
.
01111111 = 0xBD07_FFFF

bit 11-4 **Reserved**: Write '1'

bit 3 **ICESEL**: In-Circuit Emulator/Debugger Communication Channel Select bit

1 = PGEC2/PGED2 pair is used
0 = PGEC1/PGED1 pair is used

bit 2 **Reserved**: Write '1'

bit 1-0 **DEBUG<1:0>**: Background Debugger Enable bits (forced to '11' if code-protect is enabled)

11 = Debugger disabled
10 = Debugger enabled
01 = Reserved (same as '11' setting)
00 = Reserved (same as '11' setting)

PIC32MX3XX/4XX

29.1 DC Characteristics

TABLE 29-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp. Range (in °C)	Max. Frequency
			PIC32MX3XX/4XX
DC5	2.3V-3.6V	-40°C to +85°C	80 MHz (Note 1)
DC5b	2.3V-3.6V	-40°C to +105°C	80 MHz (Note 1)

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

TABLE 29-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-Temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S ({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 29-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin XBGA (10x10x1.1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 100-Pin TQFP (12x12x1 mm)	θJA	43	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP (10x10x1 mm)	θJA	47	—	°C/W	1
Package Thermal Resistance, 64-Pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 29-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp					
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	Supply Voltage	2.3	—	3.6	V	—
DC12	VDR	RAM Data Retention Voltage (Note 1)	1.75	—	—	V	—
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	1.75	—	1.95	V	—
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

PIC32MX3XX/4XX

TABLE 29-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾		Min.	Max.	Units	Conditions	
TB10	TtXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TtXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	
TB15	TtXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of 25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 29-23: EJTAG TIMING CHARACTERISTICS

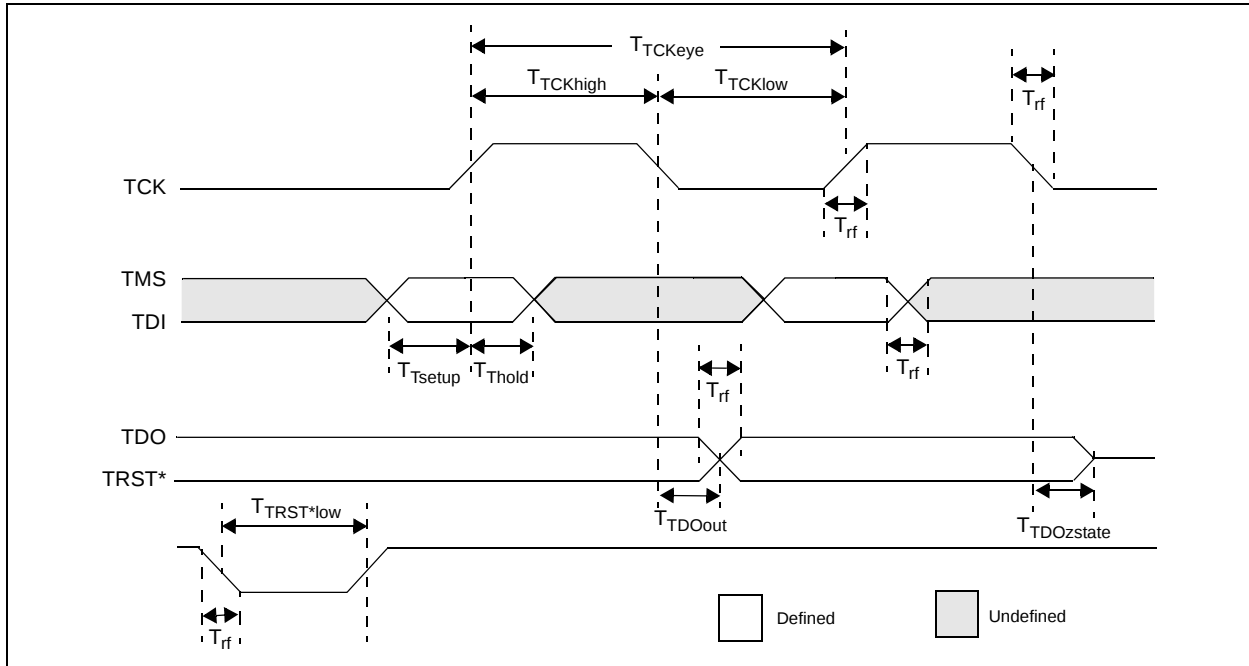


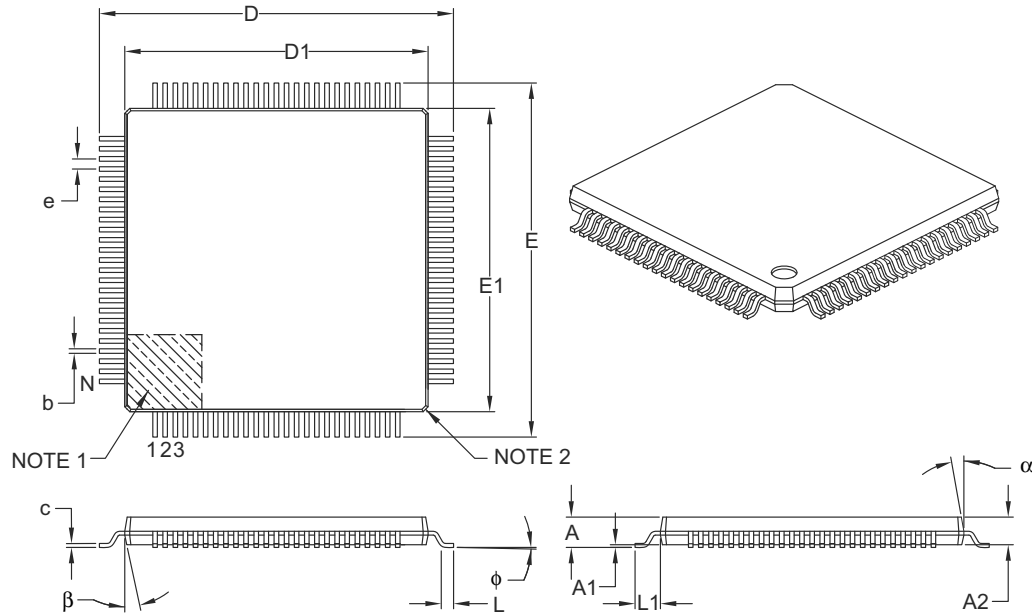
TABLE 29-41: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp		
Param. No.	Symbol	Description ⁽¹⁾	Min.	Max.	Units	Conditions
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	14.00 BSC		
Overall Length	D	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Molded Package Length	D1	12.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

PIC32MX3XX/4XX

TABLE A-3: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 “Electrical Characteristics”	Added the new V-Temp temperature range (-40°C to +105°C) to the heading of all specification tables. Updated the Ambient temperature under bias, updated the Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 2.3V, and added Voltage on V_{BUS} with respect to V_{SS} in Absolute Maximum Ratings. Added the characteristic, DC5a to Operating MIPS vs. Voltage (see Table 29-1). Updated or added the following parameters to the Operating Current (I_{DD}) DC Characteristics: DC20, DC23, DC24c, DC25d, DC26c (see Table 29-5). Added the following parameters to the Idle Current (I_{IDLE}) DC Characteristics: DC30c, DC31c, DC32c, DS33c, DC34c, DC35c, and DC36c (see Table 29-6). Added the following parameters to the Power-down Current (I_{PD}) DC Characteristics: DC40g, DC40h, DC40i, DC41g, DC41h, DC42g, DC42h, DC42i, DC43h, and DC43i (see Table 29-7). Added the Brown-out Reset (BOR) Electrical Characteristics (see Table 29-10). Removed all Conditions from the Program Memory DC Characteristics (see Table 29-11). Removed the AC Characteristics voltage reference table (Table 29-15). Added Note 2 to the PLL Clock Timing Specifications (see Table 29-18). Updated the OC/PWM Module Timing Characteristics (see Figure 29-9). Added parameter IM51 and Note 3 to the I2Cx Bus Data Timing Requirements (Master Mode) (see Table 29-32). Added parameter numbers (AD13, AD14, and AD15) to the ADC Module Specifications (see Table 29-34). Updated the 10-bit ADC Conversion Rate Parameters (see Table 29-35). Updated parameter AD57 (T_{SAMP}) in the Analog-to-Digital Conversion Timing Requirements (see Table 29-36). Updated the Conditions for parameters USB313, USB318, and USB319 in the OTG Electrical Specifications (see Table 29-40).
Section 30.0 “Packaging Information”	Updated the 64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] packing diagram.
Product Identification System	Added the new V-Temp (V) temperature information.